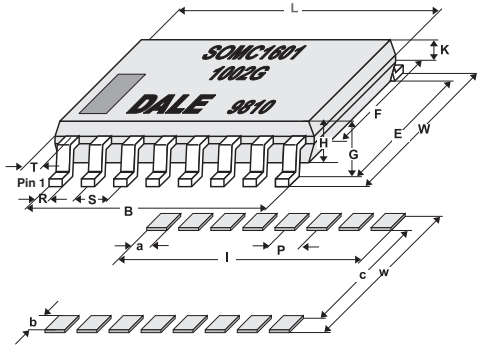


16-TERMINAL DEVICE



SOLDER PAD DIMENSIONS [in millimeters]						
	a	b	c	l	p	w
WAVE	0.64	1.91	5.34	9.53	1.27	9.15
REFLOW	0.64	1.91	5.34	9.53	1.27	9.15

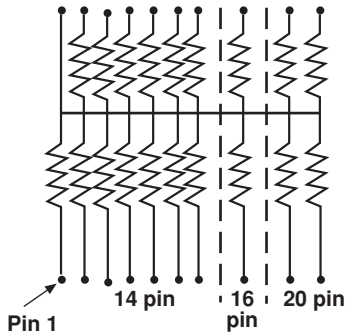
The dimensions shown are for 16 pin part. For parts with different pin numbers use the same pitch and add or subtract pads as required.

Note: Maximum solder reflow temperature + 255°C

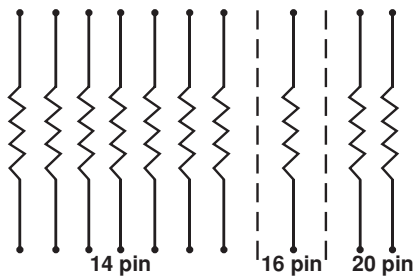
DIMENSIONS [in millimeters]											
PIN NO#	L	W	B	E	F	G	H	K	R	S	T
14	9.91	7.62	7.62	6.20	5.59	2.16	2.03	0.914	0.457	1.27	1.14
16	11.18	7.62	8.89	6.20	5.59	2.16	2.03	0.914	0.457	1.27	1.14
20	13.72	7.62	11.43	6.20	5.59	2.16	2.03	0.914	0.457	1.27	1.14
Tol	± 0.254	± 0.381	± 0.254	± 0.381	± 0.127	± 0.127	± 0.127			± 0.254	

CIRCUIT SCHEMATICS

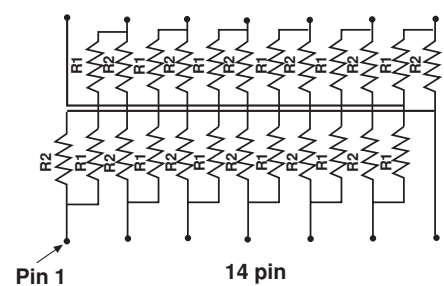
01 Circuit



03 Circuit



05 Circuit



PERFORMANCE		
TEST	CONDITIONS OF TEST	TEST RESULTS
Power Conditioning	MIL STD-202	± 0.5%
Load Life at 70°C	MIL STD-202	± 0.5%
Short Time Overload	MIL STD-202	± 0.25%
Thermal Shock	MIL STD-202	± 0.5%
Moisure Resistance	MIL STD-202	± 0.5%
Resistance to Soldering Heat	MIL STD-202	± 0.25%
Low Temperature Operation	MIL STD-202	± 0.25%
Vibration	MIL STD-202	± 0.25%
Shock	MIL STD-202	± 0.25%
Terminal Strength	MIL STD-202	± 0.25%